ABSTRACT OF THE DISCLOSURE

On an inner side of a mounting pad on a circuit substrate, a plurality of solder resist zones are disposed to project from the substrate. Sealing resin is applied by one-point coating onto a central position of the solder resist zones. A semiconductor device is place on the substrate. While heating the resin under pressure, the semiconductor device is mounted on the substrate. Therefore, the sealing resin is supplied to each vertices of the projecting solder resist zones disposed in circumferential areas on the substrate, and hence a filet is uniformly formed on the substrate. In the LSI semiconductor device mounting process using pressure welding, highly reliable connection can be achieved by one-point coating using a dispenser at a low cost with high productivity.

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